

Public Products List

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PCN Title : ST Muar (Malaysia) Additional capacity through High Density Matrix Leadframe for STM8A AUTOMOTIVE listed products in LQFP 64 10x10 package *PCN Reference :* MDG/22/13076

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM8AF5269TAY	STM8AF6289TCX	STM8AF52A9TDY
STM8AF5289TCX	STM8AF6289TCY	STM8AF62A9TCY
STM8AF6269TCX	STM8AF52A9TCY	STM8AF6289TAY
STM8AF5269TAX	STM8AF62A9TDY	STM8AF6269TCY
STM8AF5289TCY	STM8AF6269TAY	STM8AF5289TAY
STM8AF52A9TCX	STM8AF52A9TAY	STM8AF62A9TCX

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PRODUCT/PROCESS CHANGE NOTIFICATION PCN13076– Additional information

ST Muar (Malaysia) Additional capacity through High Density Matrix Leadframe for STM8A AUTOMOTIVE listed products in LQFP 64 10x10 package

MDG - Microcontrollers Division (MCD)

What is the change?

	Current back-end lines	New back-end line			
Assembly site	ST Muar (Malaysia)				
wire	Gold 1.0 mil	Gold 0.8 mil			
Leadframe	Matrix	High Density			
Leadfinishing	Spot Ag, postplated (e3)	Ring Ag, postplated (e3)			
Resin (1)	Sumitomo G700L	Sumitomo G700LS			
Glue	LOCTITE ABLESTIK QMI9507-2A1	Hitachi EN4900GC			
Enhanced		2 digits SS marking			
Traceability in	No digit	2D marking			
marking					

(1) Package darkness changes depending on molding compound.

Pin1 identifier can change in terms of form and positioning.

Marking position and size could be different upon assembly line, without any loss of information.



How can the change be seen?

	No Digit	With Enhanced Tracability (2D & SS) marking		
Marking example	 PP LLL WX COO TF Y WW	e3 2D PP LLL WX R COO TF Y WW SS		

PP code indicates the Assembly traceability plant code.

PP code	Assembly Line - Fab
99	ST Muar (Malaysia)



How to order samples?

For all samples request linked to this PCN, please:

- place a <u>Non-standard</u> sample order (choose Sample Non Std Type from pull down menu)
- insert the PCN number "PCN13076" into the NPO Electronic Sheet/Regional Sheet
- request sample(s) through Notice tool, indicating a single Commercial Product for each request

	rtial Ship: 01 - Price Pol: 05 Status: 01 Canc:
	2: O Sample Type: Sample Non Std Type V
	Closing Type: Sample Std Type Sample Non Std Type
	Sample Non Std w Spi Tests
	Lab Sheet:
SO NPO Sample	
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Header	
SO Nr: 8018502433 C	ustomer: 99770200 01 ST-TOKYO SO Type: 30 Sample Order Cost Center: JT3129 SAMPLES /SALES J
PO Nr.	Carrier Code: 0001 Price Policy: 05 Currency: 02 LS. DOLLAR - Reg Name:
Notes:	Status: 01 All items pending.ni Issuing Date: 25JUN-2018 Ord Vet: 0.0000 Sample Reg Date: 25Jun-2018
Sch I Nr PO L Nr.	Finished Good [Comm Qty] Open Qty [Plant Open Qty] Reqd Qty [Unit Price] BD CD EDD St
	M32F429NIH6 30 30 30 30 0.0000 25-Jun-18 01-Mar-59 01-Mar-59 01-
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Final Cust	
PO Item: 000001 Comm Pro	dt: STM32F429NIH6 Rty: 30 RD: 25Jun-18 Unit Price: 0.0000 Final Cust: 8800367006 SANSHIN/NPC
Cust Part Nr:	Finishd Good: Partial Ship: 01 v Price Pol: 05 Status 01 Cane:
Notes:	TAM K Pieces: 0 Dur Share 2: 0 Sample Type: Sample Non Std Type
Project Name:	Clozing Date: Clozing Type:
Reg	onal Sheet: Lab Sheet:
PCN 10595	



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RER2214 for PCN13076 ST MUAR – LQFP10x10 64L Automotive MTX to HD conversion (Gold wires)

Reliability Evaluation Plan

August 25th, 2022 MDG GPM Quality & Reliability

RER2214 - ST MUAR - LQFP10x10 64L Automotive MTX to HD conversion Package Test Vehicles

Package line	Assembly Line	Package	Device (RawLine Code)	Diffusion Process Plant	Number of Reliability Lots
LQFP	LQFP 10*10	64L	STM8 (JJ5W*79AZ25T)	CMOS F9 G01 ST RSST 8	3



RER2214 - ST MUAR - LQFP10x10 64L Automotive MTX to HD conversion Extract AEC – Q100 Reliability flow

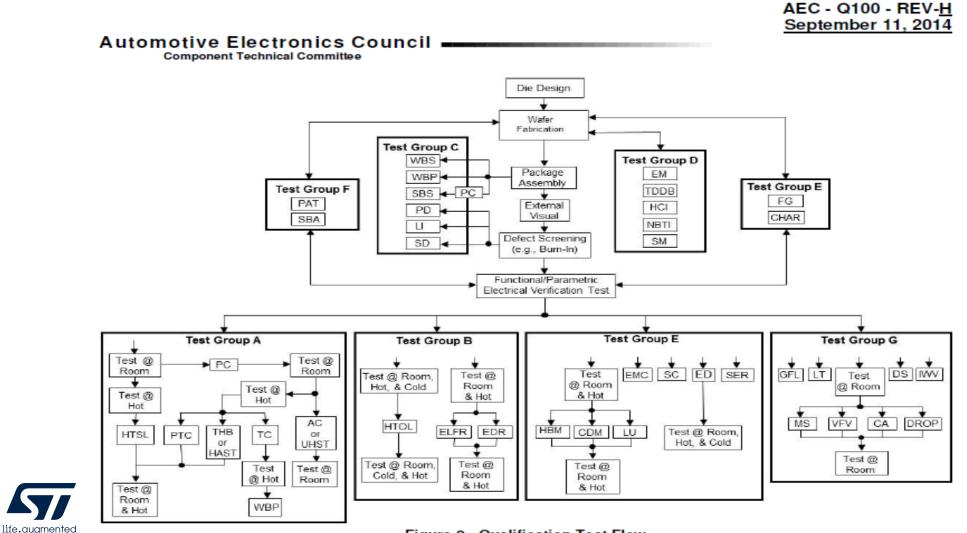


Figure 2: Qualification Test Flow

RER2214 - ST MUAR - LQFP10x10 64L Automotive MTX to HD conversion Package Reliability Trials (1/2)

Reliability Trial & Standards		Test Conditions	Pass Criteria	Unit per Lot	Lot qty	More critical constraints for components
PC	Pre Conditioning: Moisture Sensitivity Jedec Level 3 J-STD-020/ JESD22-A113	Bake (125°C / 24 hrs) Soak (30°C / 60% RH / 192 hrs) for level 3 Convection reflow: 3 passes	3 passes MSL3	244	3	T0 test @ Room
uHAST (*)	UnBiased Highly Accelerated Temperature and Humidity Stress AEC-Q100 - JESD22 A118	130°C, 85%RH, 2 atm	96h	77	3	Read out after PC @ Room Read out 96h @ Room
TC(*)	Thermal Cycling AEC-Q100 - JESD22 A104	-55°C +150°C or equivalent	G0: 2000cy	90	3	Read out after PC @ Room + Hot Read out 1000cy/2000cy @ Hot
Wire Bond Pull after TC	Mil Std 883 Method 2011	Minimum pull strength after TC=3 grams	0cy/1000cy/ 2000cy	30 bonds from a minimum	3	5 devices @ 0cy/ 5 devices @ 1000cy/ 5 devices @ 2000cy
Wire Bond Shear after TC	AEC Q100-001	Min bond shear 15g	0cy/1000cy/ 2000cy	of 5 devices 30	3	5 devices @ 0cy/ 5 devices @ 1000cy/ 5 devices @ 2000cy



RER2214 - ST MUAR - LQFP10x10 64L Automotive MTX to HD conversion Package Reliability Trials (2/2)

Reliability Trial & Standards		Test Conditions	Pass Criteria	Unit per Lot	Lot qty	More critical constraints for components
ТНВ (*)	Temperature Humidity Bias AEC-Q100 - JESD22-A101	85°C, 85% RH, bias, 5,6V	1000h	77	3	Read out after PC @ Room + Hot Read out 500h/1000h @ Room + Hot
HTSL	High Temperature Storage Life AEC-Q100 - JESD22 A103	150°C- no bias	G0: 2000h	77	3	T0 test @ Room + Hot Read out 1000h/2000h @ Room + Hot
Construction analysis	JESD 22B102 JESDB100/B108 ST internal spec	including Solderability, Physical dimensions, wire bond shear, wire pull test, lead integrity			1 full CA	
ESD	ESD Charge Device Model AEC-Q100-011 – ANSI/ESD STM5.3.1	Aligned with device datasheet	750V corner pins / 500V others	3	3	T0 test @ Room + Hot Read out after ESD @ Room + Hot



(*) tests performed after preconditioning

RER2214 - ST MUAR - LQFP10x10 64L Automotive MTX to HD conversion Die Reliability Trials

Reliability Trial & Standards		Test Conditions	Pass Criteria	Unit per Lot	Lot qty	More critical constraints for components
ELFR	AEC-Q100-008 JESD22-A108	G0: 24h 150°c 2.2V	24h	800	1	T0 test @ Room + Hot Read out 24h @ Room + Hot
HTOL	AEC-Q100-005 JESD22-A108	G0: 1200h 150°c 2.2V	1200h	77	1	T0 test @ Room + Hot + Cold Read out 600/1200h @ Room + Hot + Cold



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